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Kind regards,

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74LVCU04A

Hex unbuffered inverter

Rev. 8 — 18 December 2015

Product data sheet

1. General description

The 74LVCU04A is a general purpose hex unbuffered inverter. Each of the six inverters is a single stage with unbuffered outputs.

2. Features and benefits

- Wide supply voltage range from 1.2 V to 3.6 V
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A (2.3 V to 2.7 V)
 - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ♦ MM JESD22-A115-B exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

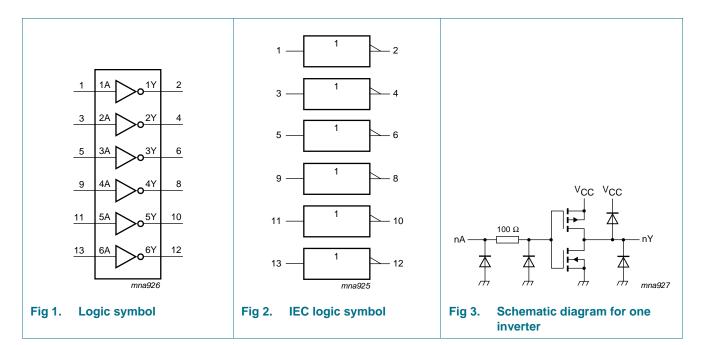
3. Ordering information

Table 1. Ordering information

Type number	Package	Package									
	Temperature range	Name	Description	Version							
74LVCU04AD	–40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1							
74LVCU04ADB	–40 °C to +125 °C	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1							
74LVCU04APW	–40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1							
74LVCU04ABQ	–40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85$ mm	SOT762-1							

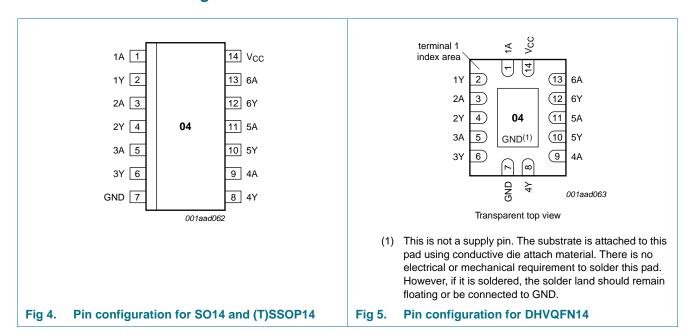


4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A, 4A, 5A, 6A	1, 3, 5, 9, 11, 13	data input
1Y, 2Y, 3Y, 4Y, 5Y, 6Y	2, 4, 6, 8, 10, 12	data output
GND	7	ground (0 V)
V _{CC}	14	supply voltage

6. Functional description

Table 3. Function table [1]

Input nA	Output nY
L	Н
Н	L

^[1] H = HIGH voltage level; L = LOW voltage level

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{CC}	supply voltage			-0.5	+6.5	V
I _{IK}	input clamping current	V _I < 0 V		-50	-	mA
VI	input voltage		<u>[1]</u>	-0.5	+6.5	V
I _{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V		-	±50	mA
Vo	output voltage		[2]	-0.5	V _{CC} + 0.5	V
I _O	output current	$V_O = 0 V \text{ to } V_{CC}$		-	±50	mA
I _{CC}	supply current			-	100	mA
I_{GND}	ground current			-100	-	mA
T _{stg}	storage temperature			-65	+150	°C
P _{tot}	total power dissipation	$T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$	[3]	-	500	mW

^[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

^[2] The output voltage ratings may be exceeded if the output current ratings are observed.

^[3] For SO14 packages: above 70 °C the value of P_{tot} derates linearly with 8 mW/K. For (T)SSOP14 packages: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K. For DHVQFN14 packages: above 60 °C the value of P_{tot} derates linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
VI	input voltage		0	-	5.5	V
Vo	output voltage		0	-	V _{CC}	V
T _{amb}	ambient temperature	in free air	-40	-	+125	°C
Δt/ΔV	input transition rise and fall	V _{CC} = 1.65 V to 2.7 V	0	-	20	ns/V
	rate	V _{CC} = 2.7 V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40	°C to +8	5 °C	-40 °C to	+125 °C	Unit
			Min	Typ[1]	Max	Min	Max	
V _{IH}	HIGH-level	$V_{OL(max)} = 0.5 \text{ V}; I_{O} = -100 \mu\text{A}$						
	input voltage	V _{CC} = 1.2 V	1.08	-	-	1.12	-	V
		V _{CC} = 1.65 V to 1.95 V	1.3	-	-	1.5	-	V
		V _{CC} = 2.3 V to 2.7 V	1.8	-	-	2.0	-	V
		V _{CC} = 3.0 V	2.0	-	-	2.4	-	V
		V _{CC} = 3.6 V	2.4	-	-	2.8	-	V
V _{IL} LOW-level input voltage	LOW-level input voltage	$V_{OH(min)} = V_{CC} - 0.5 \text{ V};$ $I_O = -100 \mu\text{A}$						
		V _{CC} = 1.2 V	-	-	0.12	-	0.1	V
		V _{CC} = 1.65 V to 1.95 V	-	-	0.6	-	0.4	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.6	-	0.5	V
		V _{CC} = 3.0 V	-	-	1.0	-	0.6	V
		V _{CC} = 3.6 V	-	-	1.2	-	0.7	V
V _{OH}	HIGH-level	V _I = GND						
	output	$V_{CC} = 3.0 \text{ V}; I_{O} = -100 \mu\text{A}$	V _{CC} - 0.2	-	-	V _{CC} - 0.3	-	V
	voltage	$V_{CC} = 1.65 \text{ V}; I_{O} = -4 \text{ mA}$	1.2	-	-	1.05	-	V
		$V_{CC} = 2.3 \text{ V}; I_{O} = -8 \text{ mA}$	1.8	-	-	1.65	-	V
		$V_{CC} = 2.7 \text{ V}; I_{O} = -12 \text{ mA}$	2.2	-	-	2.05	-	V
		$V_{CC} = 3.0 \text{ V}; I_{O} = -18 \text{ mA}$	2.4	-	-	2.25	-	V
		$V_{CC} = 3.0 \text{ V}; I_{O} = -24 \text{ mA}$	2.2	-	-	2.0	-	V

Table 6. Static characteristics ... continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

		-			-			
Symbol	Parameter	Conditions	-40	°C to +8	5 °C	-40 °C to	o +125 °C	Unit
			Min	Typ[1]	Max	Min	Max	
V _{OL}	LOW-level	$V_I = V_{CC}$						
	output	$V_{CC} = 3.0 \text{ V}; I_{O} = 100 \mu\text{A}$	-	-	0.20	-	0.60	V
	voltage	$V_{CC} = 1.65 \text{ V}; I_{O} = 4 \text{ mA}$	-	-	0.45	-	0.65	V
		$V_{CC} = 2.3 \text{ V}; I_{O} = 8 \text{ mA}$	-	-	0.60	-	0.80	V
		$V_{CC} = 2.7 \text{ V}; I_{O} = 12 \text{ mA}$	-	-	0.40	-	0.30	V
		$V_{CC} = 3.0 \text{ V}; I_{O} = 24 \text{ mA}$	-	-	0.55	-	0.80	V
I _I	input leakage current	$V_{CC} = 3.6 \text{ V}; V_I = 5.5 \text{ V or GND}$	-	±0.1	±5	-	±20	μА
Icc	supply current	$V_{CC} = 3.6 \text{ V}; V_I = V_{CC} \text{ or GND};$ $I_O = 0 \text{ A}$	-	0.1	10	-	40	μΑ
Δl _{CC}	additional supply current	per input pin; V_{CC} = 2.7 V to 3.6 V; V_I = V_{CC} - 0.6 V; I_O = 0 A	-	5	500	-	5000	μΑ
Cı	input capacitance	$V_{CC} = 0 \text{ V to } 3.6 \text{ V};$ $V_I = \text{GND to } V_{CC}$	-	5.5	-	-	-	pF

^[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see <u>Figure 9</u>.

Symbol	Parameter	Conditions	Conditions			5 °C	-40 °C to	Unit	
						Max	Min	Max	
t _{pd}	propagation delay	nA to nY; see Figure 6	[2]						
		V _{CC} = 1.2 V		-	6.0	-	-	-	ns
		V _{CC} = 1.65 V to 1.95 V		0.3	3.7	7.8	0.3	9.0	ns
		V _{CC} = 2.3 V to 2.7 V		0.5	2.2	4.4	0.5	5.2	ns
		V _{CC} = 2.7 V		0.5	2.0	4.5	0.5	6.0	ns
		V _{CC} = 3.0 V to 3.6 V		0.5	2.0	4.0	0.5	5.0	ns
t _{sk(o)}	output skew time	$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	[3]	-	-	1.0	-	1.5	ns
C_{PD}	power dissipation	per inverter; V _I = GND to V _{CC}	[4]						
	capacitance	V _{CC} = 1.65 V to 1.95 V		-	2.3	-	-	-	pF
		V _{CC} = 2.3 V to 2.7 V		-	5.5	-	-	-	pF
		V _{CC} = 3.0 V to 3.6 V		-	8.4	-	-	-	pF

^[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.

$$P_D = C_{PD} \times V_{CC}{}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}{}^2 \times f_o) \text{ where:}$$

 f_i = input frequency in MHz; f_o = output frequency in MHz

 C_L = output load capacitance in pF

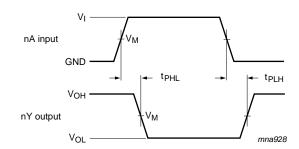
^[2] t_{pd} is the same as t_{PLH} and t_{PHL} .

^[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

^[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$\begin{split} &V_{CC} = \text{supply voltage in Volts} \\ &N = \text{ number of inputs switching} \\ &\Sigma(C_L \times V_{CC}{}^2 \times f_o) = \text{sum of the outputs} \end{split}$$

11. Waveforms

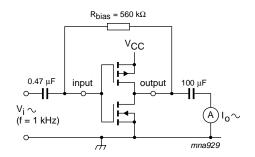


 V_{M} = 1.5 V at $V_{CC} \geq$ 2.7 V;

 $V_M = 0.5 \times V_{CC}$ at $V_{CC} < 2.7 V$;

 V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

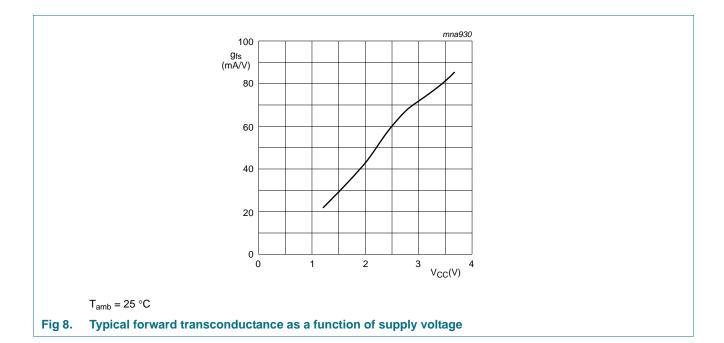
Fig 6. Input (nA) to output (nY) propagation delays

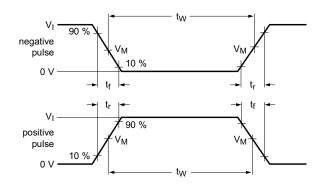


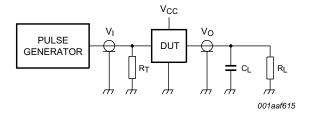
$$g_{fs} = \frac{dI_O}{dV_I}; at \ constant \ V_O$$

 $f_i = 1 \text{ kHz at } V_O \text{ is constant}$

Fig 7. Test setup for measuring forward transconductance







Test data is given in Table 8.

Definitions for test circuit:

 R_L = Load resistance.

 C_L = Load capacitance including jig and probe capacitance.

 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

Fig 9. Test circuit for measuring switching times

Table 8. Test data

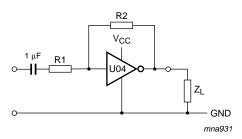
Supply voltage	Input		Load			
	V _I	t _r , t _f	CL	R _L		
1.2 V	V _{CC}	≤ 2 ns	30 pF	1 kΩ		
1.65 V to 1.95 V	V _{CC}	≤ 2 ns	30 pF	1 kΩ		
2.3 V to 2.7 V	V _{CC}	≤ 2 ns	30 pF	500 Ω		
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω		
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω		

12. Application information

12.1 Application diagrams

Some applications for the 74LVCU04A are:

- Linear amplifier: see Figure 10
- Crystal oscillator designs; see Figure 11
- Astable multivibrator; see Figure 12



 $V_{o(p-p)} = V_{CC} - 1.5 \text{ V}$ centered at $0.5V_{CC}$.

$$A_u = -\frac{G_{OL}}{I + \frac{RI}{R2}(I + G_{OL})}$$

 G_{OL} = loop gain.

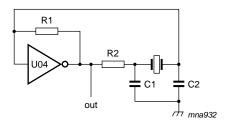
 A_u = voltage amplification.

 $R1 \geq 3~k\Omega,~R2 \leq 1~M\Omega$

 $Z_L > 10 \text{ k}\Omega; A_{OL} = 20 \text{ (typ.)}$

Typical unity gain bandwidth product is 5 MHz.

Fig 10. 74LVCU04A used as linear amplifier



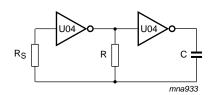
 $C_1 = 47 pF (typical)$

 $C_2 = 22 pF (typical)$

 $R_1 = 1$ to 10 M Ω (typical)

 R_2 optimum value depends on the frequency and required stability against changes in V_{CC} or average minimum I_{CC} (I_{CC} is typically 2 mA at V_{CC} = 3 V and f = 1 MHz)

Fig 11. 74LVCU04A used as crystal oscillator



$$f = \frac{1}{T} \approx \frac{1}{2.2RC}$$

 $R_S \approx 2R$.

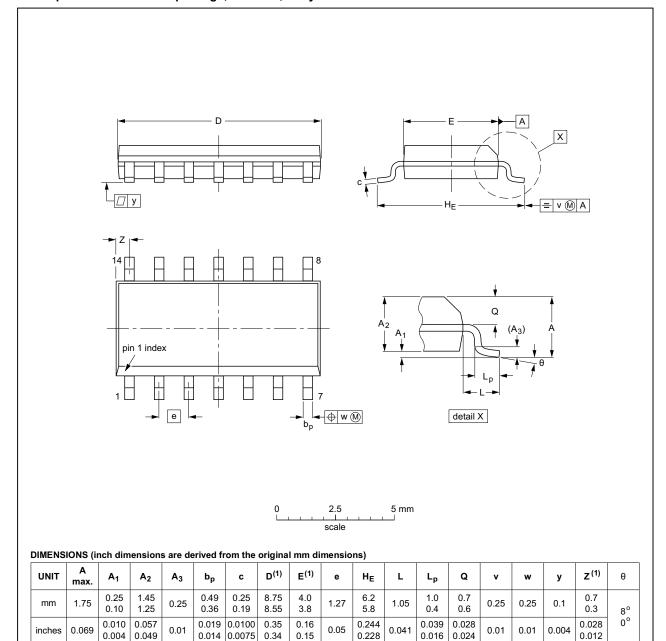
The average I_{CC} is approximately 3.5 + 0.05f (MHz) \times C (pF) [mA] at V_{CC} = 3.0 V.

Fig 12. 74LVCU04A used as a stable multivibrator

13. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



Note

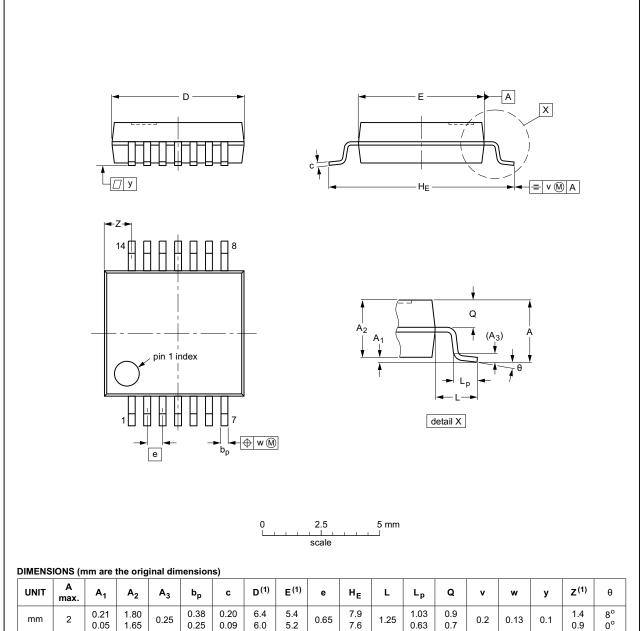
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

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VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT108-1	076E06	MS-012				99-12-27 03-02-19

Fig 13. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



UNIT	A max.	A ₁	A ₂	A ₃	b _p	U	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	>	w	у	Z ⁽¹⁾	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

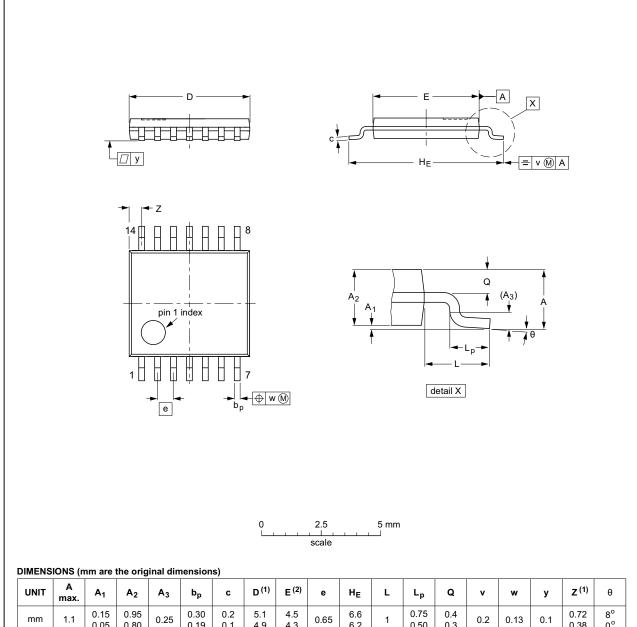
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	VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
	SOT337-1		MO-150				99-12-27 03-02-19

Fig 14. Package outline SOT337-1 (SSOP14)

74LVCU04A

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E (2)	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT402-1		MO-153				99-12-27 03-02-18	

Fig 15. Package outline SOT402-1 (TSSOP14)

74LVCU04A

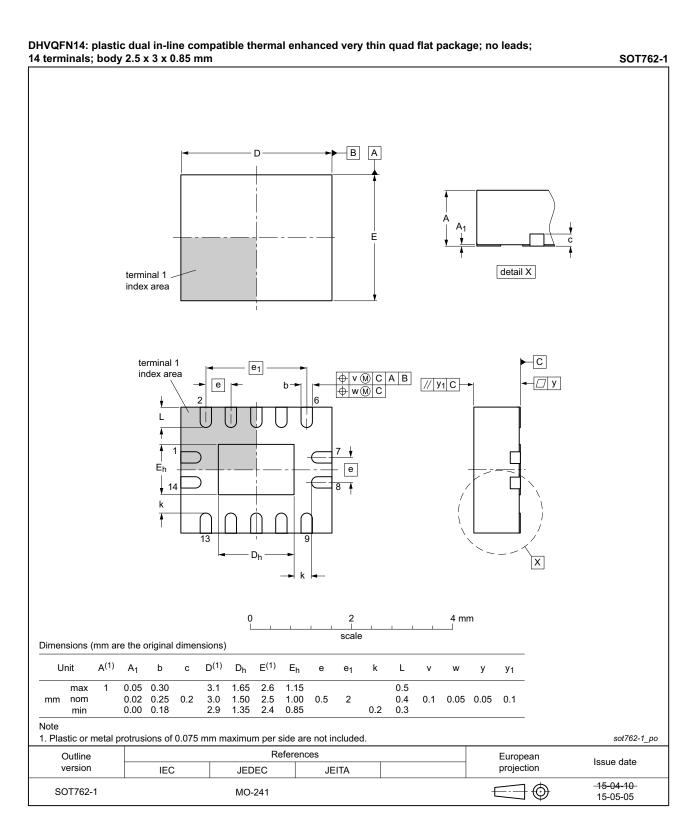


Fig 16. Package outline SOT762-1 (DHVQFN14)



14. Abbreviations

Table 9. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
НВМ	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

15. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes				
74LVCU04A v.8	20151218	Product data sheet	-	74LVCU04A v.7				
Modifications:	 Descriptive title upd 	ated. Added "unbuffered"	(errata).					
74LVCU04A v.7	20111117	Product data sheet	-	74LVCU04A v.6				
Modifications:	Legal pages updated.							
	 <u>Table 6</u>, bodyrow ΔI 	$_{ m CC}$: condition $ m V_{CC}$ change	ed.					
74LVCU04A v.6	20110809	Product data sheet	-	74LVCU04A v.5				
74LVCU04A v.5	20040312	Product specification	-	74LVCU04A v.4				
74LVCU04A v.4	20030901	Product specification	-	74LVCU04A v.3				
74LVCU04A v.3	19980729	Product specification	-	74LVCU04A v.2				
74LVCU04A v.2	19980729	Product specification	-	74LVCU04A v.1				
74LVCU04A v.1	19980729	Product specification	-	-				

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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